Celanese
The chemistry inside innovation™

CELCON® M450

Very high flow, fast cycling, has been replaced by Hostaform® C 52021
Celcon® acetal copolymer grade M450 is an extremely low viscosity grade for optimal cycle performance in very thin walls or long, narrow flow paths in injection molding.
Chemical abbreviation according to ISO 1043-1: POM

Rheological properties

Melt volume-flow rate	39	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.2	%	ISO 294-4, 2577
Moulding shrinkage, normal	2.0	%	ISO 294-4, 2577

Typical mechanical properties

Tensile Modulus	2900	MPa	ISO 527-1/-2
Yield stress, 50mm/min	66	MPa	ISO 527-1/-2
Yield strain, 50mm/min	7.5	%	ISO 527-1/-2
Flexural Modulus	2800	MPa	ISO 178
Shear Modulus	1000	MPa	ISO 6721
Charpy notched impact strength, 23°C	4.4	kJ/m^2	ISO 179/1eA
Izod notched impact strength, 23°C	4.7	kJ/m^2	ISO 180/1A

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temp. of deflection under load, 1.8 MPa	103	°C	ISO 75-1/-2
Temp. of deflection under load, 0.45 MPa	156	°C	ISO 75-1/-2
Vicat softening temperature, 50°C/h, 50N	161	°C	ISO 306

Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.75	%	Sim. to ISO 62
Density	1410	kg/m^3	ISO 1183

Injection

Drying Temperature	100 - 120	°C	
Drying Time, Dehumidified Dryer	3 - 4	h	
Melt Temperature Optimum	180	°C	Internal
Max. mould temperature	80 - 120	°C	
Back pressure	4	MPa	
Injection speed	medium		

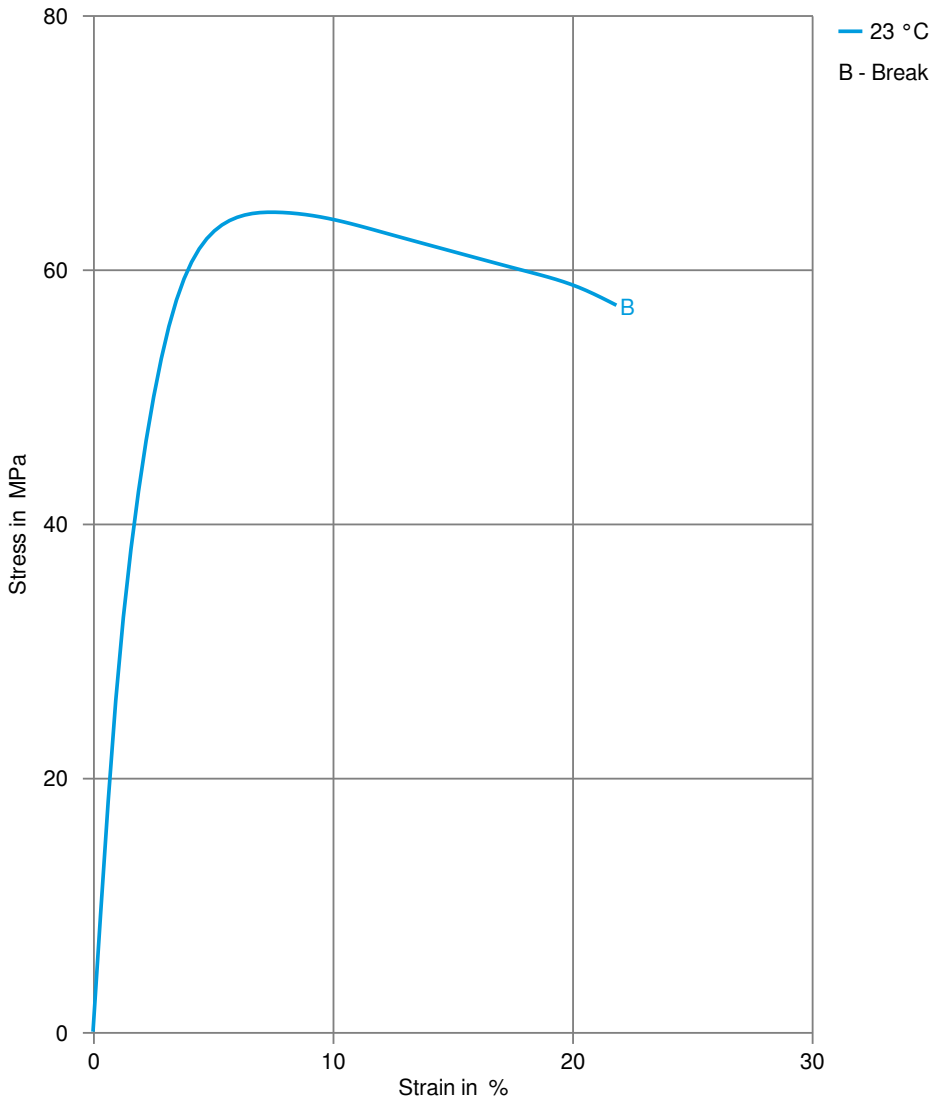
CELCON® M450

Additional information

Injection molding	Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material. Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F). Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.

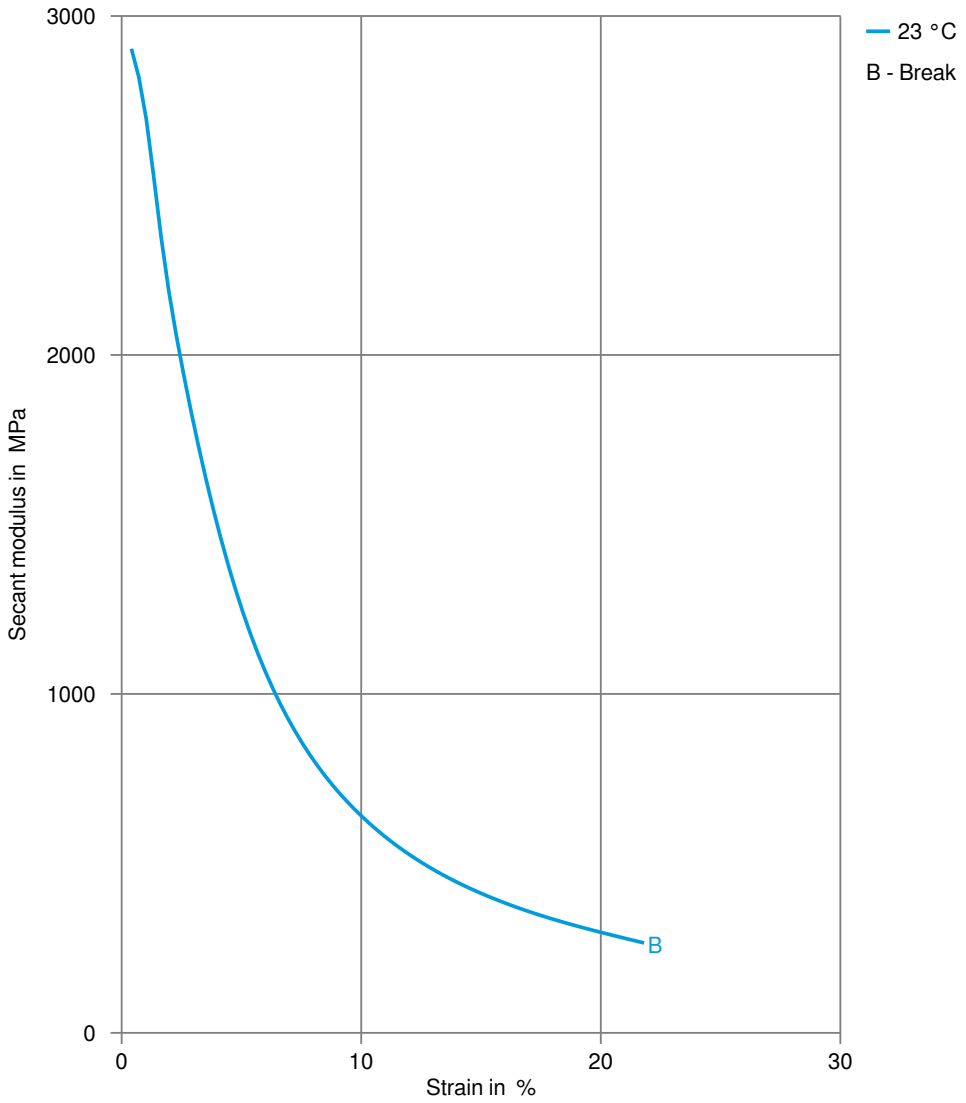
CELCON® M450

Stress-strain



CELCON® M450

Secant modulus-strain



CELCON® M450

Processing Texts

Pre-drying	Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.
Injection molding	Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material. Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F). Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.
Injection molding Preprocessing	Drying is generally not required because Celcon® and Hostaform® acetal copolymers are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%
Injection molding Postprocessing	Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

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